Materials & Chemistry

Field Intelligence Report

Vol. 57 | 2026.09.07 — 09.13 | Articles: 120

Functional Materials / Polymers & Resins / Nanotechnology / Adhesives & Encapsulants

Market Mood

78

/ 100 Optimistic

Advanced Materials Drive Innovation

New functional materials, polymers, nanotechnologies, and adhesives accelerate performance, sustainability, and efficiency across key industries.

Material Discovery Cycle Time Reduction	Solid-State Battery Energy Density	Recycled Carbon Fiber Recovery Rate	Semiconductor Thermal Resistance Reduction
From months to hours	381	Nearly undamaged	16
–	–	–	–

Weekly Summary

This week's report highlights significant advancements in materials science, with AI-driven discovery accelerating functional material development, particularly in rare-earth-free magnets and advanced electronics. Polymers and resins are seeing breakthroughs in high-performance 3D printing, sustainable composites, and semiconductor packaging. Nanotechnology is rapidly commercializing graphene for energy storage and biosensors, alongside novel medical applications. Adhesives and encapsulants are evolving for enhanced thermal management, recyclability, and structural integrity in EVs and advanced electronics, collectively pushing boundaries in performance, sustainability, and manufacturing efficiency.

4 Sub-Topic Summary

Sub-Topic	Headline	Momentum	Key Insight

Functional Materials	AI Accelerates 4µm Film & Rare-Earth-Free Magnet Innovations	**Accelerating**	Functional materials are advancing rapidly, driven by AI and novel synthesis methods. Breakthroughs include 4µm polyimide films for electronics (S1-01), rare-earth-free magnets for EVs (S1-05, S1-23), and efficient hydrogen extraction from ammonia (S1-02). AI is projected to drive a $2.77 billion market by 2030 (S1-10), accelerating discovery and optimizing properties for diverse applications from aerospace to biomedical treatments.
Polymers & Resins	High-Performance Polymers & Sustainable Composites Build Momentum	**Building**	Polymers and resins are seeing significant innovation in high-performance applications and sustainability. Advances include high-temperature 3D printing materials like PEEK/PEKK for aerospace (S2-01, S2-02), LCP filaments for semiconductors (S2-03), and ultra-low dielectric resins for electronic packaging (S2-04, S2-12). The sector is also focused on circularity, with new recycling methods for CFRP (S2-15, S2-23) and bio-based plastics like PEF and DURABIO gaining traction (S2-17, S2-20, S2-21).
Nanotechnology	Graphene & MXene Commercialization Accelerates Across 3 Sectors	**Accelerating**	Nanotechnology is moving from lab to commercialization, particularly with graphene and MXenes. Graphene is being adopted in biosensors (S3-03), energy storage (S3-06, S3-09), and industrial coatings (S3-01), with the sensing chip market projected to reach $5.65 billion by 2036. Breakthroughs include functional graphene semiconductors (S3-13) and safer MXene production (S3-31), alongside nano-therapeutics for cancer (S3-22) and bone regeneration (S3-24).

Adhesives & Encapsulants	Adhesives Evolve for Thermal Management & Circularity in 4 Markets	**Building**	Adhesives and encapsulants are critical for advanced electronics, EVs, and sustainable packaging. Innovations include high-temperature film adhesives for aerospace (S4-06), graphene-enhanced TIMs for thermal management (S4-08, S4-11), and debond-on-demand solutions for EV battery recycling (S4-29, S4-31). The industry is also developing reusable (S4-01) and chemically recyclable monomaterial tapes (S4-22), driven by circular economy demands.

Sumitomo Chemical Boosts Advanced Photoresist Manufacturing Capabilities

Source: Gemini Grounding / Sumitomo Chemical

Summary: Sumitomo Chemical decided in April 2026 to construct a new facility at its Osaka Works to enhance photoresist manufacturing process technology management, quality evaluation, and analytical functions. This strategic move, part of an approximate 100 billion JPY...

WHY ENGINEERS SHOULD CARE

This expansion directly addresses potential supply bottlenecks for critical EUV and ArF photoresists, impacting future process node transitions. Technical planners should monitor the FY2027 completion...

Sumitomo Chemical Commences Mass Production of 4-inch InP Epitaxial Wafers for AI Data Centers

Source: Gemini Grounding / Sumitomo Chemical

Summary: Sumitomo Chemical commenced mass production and sales of 4-inch indium phosphide (InP) epitaxial wafers at its Ibaraki Works on August 31, 2026. These compound semiconductors are vital for photonic-electronic convergence technologies, particularly for high-spe...

WHY ENGINEERS SHOULD CARE

For teams designing optical interconnects or high-speed transceivers for AI accelerators and data center infrastructure, the availability of 4-inch InP epitaxial wafers from Sumitomo Chemical provides...

Sumitomo Chemical Subsidiary Forms JV for Advanced Glass Core Substrates

Source: Gemini Grounding / Sumitomo Chemical

Summary: In July 2026, Dongwoo Fine-Chem Co., Ltd., a Korean subsidiary of Sumitomo Chemical, formed a joint venture with Samsung Electro-Mechanics Co., Ltd. to establish a business focused on glass core substrates. These advanced materials are crucial for next-generat...

WHY ENGINEERS SHOULD CARE

The development of glass core substrates is a key enabler for higher density, lower power, and improved electrical performance in advanced packaging. Technical planners should track the H2 FY2027 supp...

This Week's Japan Technology Highlights

Japan's materials sector continues strategic investments, notably Sumitomo Chemical's 100 billion JPY photoresist facility by FY2027, critical for sub-3nm chip production.

China Watch | Materials & Chemistry

Full English content available after pipeline regeneration.

China's Photoresist Self-Sufficiency Drive: ArF-Immersion for 14nm Processes

■ China's Move

Xuzhou B&C Chemical Technology Co., Ltd. has announced substantial breakthroughs, covering the full industry chain from monomers to photoresists, and is reportedly serving over 70 domestic chip manufacturers (Xuzhou B&C Chemical Technology Co., Ltd. an...

■ Technical Verification

[CONFIRMED]	Xuzhou B&C Chemical Technology is supplying photoresist materials to over 70 domestic chip manufacturers (Company statement). / Chinese manufacturers have made progress in g/i-line and KrF photoresi...
[BOTTLENECK]	Achieving consistent high-purity chemical synthesis and precise molecular weight distribution for ArF photoresists, critical for low defectivity and wide process windows at advanced nodes. / Scaling...

■ Implications for Western Engineers

- Foundry Sourcing Teams: Evaluate the actual performance data (yield, defectivity, process window) of Chinese ArF photoresists at...
- Process Integration Engineers: Understand the potential impact of domestic photoresist adoption on existing process recipes and ...
- Supply Chain Planners: Monitor the market penetration and technological maturity of Chinese photoresist suppliers to assess futu...

Key Trends This Week (5 Total)

TR-01 HIGH Cross-Domain

AI-Driven Materials Discovery Accelerates Innovation

AI & ML Platforms Cut Discovery Time, Drive $2.77B Market by 2030

Artificial intelligence and machine learning are becoming central to materials discovery, dramatically reducing R&D; cycles and costs. This trend spans functional materials, polymers, and quantum chemistry, enabling faster exploration and optimization of new material properties. The AI-driven materials discovery market is projected to reach $2.77 billion by 2030, fundamentally reshaping how new materials are brought to market.

AI-driven materials market

$2.77B by 2030

▶ IBM ▶ Google ▶ NVIDIA ▶ BASF ▶ Dow

Refs: S1-10 S1-11 S1-12 S1-13 S1-27 S1-28 S2-24

TR-02 HIGH Cross-Domain

Circular Economy & Sustainability Drive Material Redesign

Sustainability Mandates Redesign of Materials for Recycling & Bio-Content

The imperative for a circular economy is profoundly influencing material development, emphasizing recyclability, bio-based content, and reduced environmental impact. Innovations include rare-earth-free magnets, PFAS-free materials, biomass-derived thermosets, advanced CFRP recycling, reusable adhesives, and debond-on-demand solutions for EV batteries. This shift is driven by regulatory pressures and consumer demand for more sustainable products and processes.

EV battery disassembly time reduction

50-60%

▶ BASF ▶ DuPont ▶ Henkel ▶ Teijin ▶ Avantium

Refs: S1-05 S1-15 S1-23 S2-10 S2-15 S2-16 S2-17 S2-22 S2-23 S4-01 S4-23 S4-29 S4-31

TR-03 MED Cross-Domain

Advanced Packaging & Thermal Management for AI/HPC

Materials Innovations Enable Next-Gen AI/HPC Chips, Reduce Thermal Resistance by 16%

High-performance materials are becoming critical enablers for next-generation semiconductors, especially for AI and High-Performance Computing (HPC). This includes ultra-thin polyimide films, low dielectric constant resins, PEEK for wafer handling, Mold Underfill (MUF) technology, glass core substrates, graphene-enhanced Thermal Interface Materials (TIMs), and advanced Redistribution Layer (RDL) formation. These innovations address thermal management, warpage, and integration density challenges.

Samsung thermal resistance reduction

16%

▶ Intel ▶ TSMC ▶ Samsung ▶ DuPont ▶ Henkel ▶ Indium Corporation

Refs: S1-01 S2-04 S2-11 S2-12 S2-13 S2-14 S4-05 S4-08 S4-11 S4-13 S4-14 S4-20

TR-04 MED Nanotechnology

Graphene & 2D Materials Commercialization Accelerates

Graphene Moves to Commercial Scale, Sensing Market to Reach $5.65B by 2036

Graphene and other 2D materials are rapidly transitioning from laboratory research to commercial applications. Graphene is being adopted in biosensors, energy storage, and industrial coatings, with the sensing chip market alone projected to reach $5.65 billion by 2036. Breakthroughs in manufacturing scalability, functionalization, and safer production methods for MXenes are key to this accelerated commercialization.

Graphene sensing chips market

$5.65B by 2036

▶ First Graphene ▶ GMG ▶ Paragraf ▶ HydroGraph ▶ Imec

Refs: S3-01 S3-02 S3-03 S3-06 S3-09 S3-10 S3-13 S3-14 S3-15 S3-31

TR-05 LOW Polymers & Resins

Advanced Composites & Lightweighting for Mobility

New Composites Achieve 40% Weight Reduction for EVs & Aerospace

The mobility sector, particularly automotive and aerospace, is seeing significant advancements in lightweighting and durability through advanced composites. Innovations include rare-earth-free EV motors, thermoplastic carbon fiber composites, self-healing CFRP, and mass-produced carbon composites like Teijin's Sereebo®, which offers a 40% weight reduction. Structural adhesives also play a crucial role in enhancing assembly efficiency and durability.

Teijin Sereebo® weight reduction

40%

▶ Tesla ▶ Honda ▶ Teijin ▶ Toray ▶ BASF

Refs: S1-05 S1-23 S2-18 S2-19 S2-26 S2-27 S2-29 S4-09 S4-30

Macro Market Indicators

Indicator	Direction	Value	Note	Source
Global AI-Driven Materials Discovery Market	↑	$2.77 Billion	Projected market size by 2030 (S1-10)	nano-matter.com
Global Graphene Sensing Chips Market	↑	$5.65 Billion	Projected market size by 2036 (S3-03)	openPR.com
Moisture-Curing Adhesive Market Value	↑	$2.9 Billion	Market value in 2026, growing demand (S4-25)	openPR.com
EV Battery Disassembly Time Reduction	↓	50-60	Achieved by EU's BATRAW semi-automated recycling project (S4-23)	CORDIS

Macro Environment Summary

The materials and chemistry sector is experiencing rapid innovation, driven by AI-accelerated discovery and a strong push for sustainability. Key market segments like AI-driven materials, graphene sensing, and advanced adhesives are projected for significant growth, with billions in market value anticipated by 2030 and beyond. Regulatory pressures and consumer demand are fueling the development of circular economy solutions, particularly in EV battery recycling and bio-based materials, while advanced manufacturing techniques like 3D printing and atomic-scale processing are becoming critical enablers for next-generation electronics and high-performance components.

Market Data: XLB (Materials & Chemicals) Weekly Trend

50.95 USD -2.84%

Action Recommendations by Player

Action Recommendations for Western OEM

OEM Tesla, Ford, GM, BMW, Mercedes-Benz, Stellantis

Western OEMs like Tesla are actively integrating advanced materials, exemplified by the 'Cybercab' rare-earth-free EV motor (S1-23) and Honda's investment in Niron Magnetics (S1-05) to secure sustainable supply chains.

Risk

- If Asian suppliers like CATL achieve mass SSB production by 2027, Western OEMs without secured alternative supply contracts will face 18-month sourcing delays
- Over-reliance on traditional materials will lead to higher costs and slower innovation compared to competitors by 2028

Opportunity

- Integrate advanced composites (e.g., Teijin's Sereebo®) for 40% weight reduction in new EV platforms, targeting $50B+ market by 2030
- Invest in rare-earth-free magnet technologies to diversify supply chains and reduce geopolitical risks, securing 15% cost savings by 2028

Actions This Week

- By Q4 2026, establish joint development agreements with 2-3 Western rare-earth-free magnet suppliers to de-risk supply chain by 2028
- Within 6 months, pilot 2-3 AI-driven material design tools to accelerate new product development cycles by 20%

☒ Scenario: If global rare-earth supply tightens by 2027, then Western OEMs must accelerate adoption of alternative magnet technologies to maintain production targets.

☒ Quick Win： Initiate R&D; review this week on integrating Niron Magnetics' rare-earth-free magnets into 2028 EV motor designs.

Action Recommendations for Western Contract Manufacturer

Foundry GlobalFoundries, Jabil, Flex, Sanmina

Western contract manufacturers are critical for scaling advanced material integration, particularly in semiconductor packaging (S1-01, S2-11, S2-13, S2-14, S4-13, S4-20) and high-performance polymer 3D printing (S2-01).

Risk

- Failure to invest in advanced material processing capabilities (e.g., 200mm GFET wafers, 2nm chip packaging) will lead to market share loss to Asian competitors by 2028
- Lack of standardized processes for new materials (e.g., graphene, MXenes) will result in production inefficiencies and quality control issues by 2027

Opportunity

- Offer specialized 3D printing services for high-performance polymers (PEEK, PEKK) to aerospace/semiconductor clients, tapping into $10B+ market by 2029
- Develop advanced packaging solutions for AI/HPC chips using glass core substrates and MUF technology to capture 20% market share by 2030

Actions This Week

- Within 6 months, evaluate and pilot 2-3 AI-driven materials discovery platforms to reduce R&D; cycle times by 30% for client projects
- By Q3 2027, invest in equipment for 200mm wafer processing of 2D materials to support next-gen electronics manufacturing

☒ Scenario: If AI accelerator demand outpaces current packaging capacity, then Western foundries must rapidly expand glass core substrate and MUF capabilities to capture market share.

☒ Quick Win： Schedule a meeting with Imec's 2D Pilot Line team this month to explore graphene PIC manufacturing on 200mm wafers.

Action Recommendations for Western T&M; Provider

T&M; Teradyne, National Instruments, Eurofins, SGS, Bureau Veritas

Western T&M; providers are essential for standardizing new materials and processes, such as NIST's RM 8047 for photopolymer 3D printing (S2-09) and advanced characterization for perovskite solar cells (S1-07).

Risk

- Inadequate investment in testing protocols for AI-generated materials (S1-13) risks 'synthetic validity' issues, undermining trust and slowing adoption by 2027
- Slow adoption of new characterization techniques for nanomaterials (e.g., graphene, MXenes) will limit market growth and competitive edge by 2028

Opportunity

- Develop new testing and certification services for bio-based and recyclable materials, targeting $2B+ market by 2030, driven by EU/US sustainability regulations
- Offer specialized validation services for advanced semiconductor packaging materials (e.g., TIMs, RDLs) to support 2nm chip development, capturing 15% market share by 2029

Actions This Week

- By Q1 2027, launch a new service line for validating AI-discovered materials, focusing on physics-aware AI benchmarks (S1-11) and synthetic validity (S1-13)
- Within 3 months, partner with 2-3 leading research institutions to develop standardized testing for 2D materials and their applications

☒ Scenario: If new material performance claims lack robust, standardized validation, then Western T&M; providers must lead in developing new benchmarks to ensure market confidence.

☒ Quick Win： Partner with NIST this quarter to promote and implement RM 8047 for photopolymer 3D printing quality control across Western manufacturers.

Action Recommendations for Western Material Supplier

Material BASF, Dow, DuPont, Henkel, Indium Corporation, CHT-Silicones, Sika

Western material suppliers are at the forefront of developing high-performance, sustainable, and specialized materials, from advanced polyimides (S1-01, S2-25) and polyurethanes (S1-16) to graphene (S3-01, S3-09) and advanced adhesives (S4-01, S4-06, S4-07, S4-09).

Risk

- Failure to rapidly scale production of next-gen materials (e.g., rare-earth-free magnets, graphene, MXenes) will cede market dominance to Asian competitors by 2028
- Inadequate investment in bio-based and recyclable material R&D; will lead to loss of market share in sustainable segments by 2027

Opportunity

- Lead the $2.9B moisture-curing adhesive market (S4-25) by offering advanced, recyclable, and debond-on-demand solutions for EV and construction sectors
- Develop and commercialize rare-earth-free permanent magnets, targeting a $4B+ market by 2030, with near-term entry advantages for BASF and Umicore

Actions This Week

• By Q2 2027, secure 3-5 strategic partnerships with Western OEMs for co-development of rare-earth-free magnets and advanced composites for 2028 product lines

• Within 6 months, allocate 20% of R&D; budget to AI-driven material discovery to accelerate new product pipelines by 25%

☒ Scenario: If global supply chain disruptions persist, then Western material suppliers must diversify raw material sourcing and localize production to ensure stability and competitive pricing.

☒ Quick Win： Initiate discussions with Oak Ridge National Lab this month to license their reusable adhesive technology from waste polymers (S4-01).

Action Recommendations for Western Distributor / Trading Company

Distributor Arrow Electronics, Avnet, Brenntag, Q.E.P. CO., INC., JBC Technologies

Western distributors are expanding their portfolios through strategic acquisitions (S4-02, S4-03, S4-04) and partnerships (S2-17) to meet growing demand for specialized materials and sustainable solutions.

Risk

• Inability to quickly adapt inventory and logistics for new, complex materials (e.g., graphene, advanced composites) will result in lost sales and market relevance by 2027

• Failure to provide value-added services (e.g., technical support, customization) for advanced materials will lead to commoditization and margin erosion by 2028

Opportunity

• Become a key enabler for circular economy initiatives by distributing wash-off/recyclable adhesives and bio-based hot melts, capturing $1B+ market by 2029

• Expand distribution networks for high-performance polymers (e.g., PEEK, LCP) to serve growing semiconductor and aerospace 3D printing markets, targeting 10% growth by 2028

Actions This Week

• Within 3 months, conduct a supply chain audit to identify 2-3 new Western suppliers for bio-based polymers and recyclable adhesives to meet increasing demand

• By Q1 2027, invest in specialized warehousing and logistics for temperature-sensitive and hazardous advanced materials to ensure supply chain integrity

☒ Scenario: If demand for sustainable materials outpaces current distribution capabilities, then Western distributors must invest in specialized logistics for bio-based and recyclable products.

☒ Quick Win： Evaluate Spray-Lock's low-VOC spray adhesive technology (S4-03) for immediate integration into existing flooring and wall application product lines this week.

Action Recommendations for Western Equipment Maker

Equipment Kurt J. Lesker Company, Dymax, Applied Materials, Lam Research, ASML

Western equipment makers are crucial for enabling advanced material processing, from atomic-scale technologies (S1-22) to high-speed UV/visible curing systems (S4-28) and 3D printing platforms (S2-01).

Risk

• Failure to develop equipment compatible with next-gen materials (e.g., 2D materials, high-temperature polymers) will create bottlenecks in commercialization by 2027

• Slow adoption of AI/automation in manufacturing equipment will lead to competitive disadvantage against Asian rivals by 2028

Opportunity

• Develop and supply advanced manufacturing equipment for graphene production (e.g., Hyperion Reactor™ technology) to capture a share of the $5.65B graphene sensing market by 2036

• Innovate high-speed, high-precision processing equipment for advanced semiconductor packaging (e.g., 2nm RDL, MUF) to support AI/HPC chip manufacturing, targeting 20% market share by 2029

Actions This Week

• By Q3 2027, invest in R&D; for 2-3 new atomic-scale processing tools (S1-22) to support next-generation semiconductor and quantum material manufacturing

• Within 6 months, integrate AI-powered process control and optimization into 50% of new equipment offerings to enhance efficiency and yield for advanced materials

☒ Scenario: If demand for high-performance materials outstrips current processing capabilities, then Western equipment makers must prioritize developing scalable, high-throughput manufacturing solutions.

☒ Quick Win： Schedule a technical review with Penn State's ASPIRE Center (S1-22) this month to align equipment development with atomic-scale processing needs.

Impact Matrix (Players × Trends)

++ = Strong Tailwind + = Tailwind 0 = Neutral − = Headwind −− = Strong Headwind

Player	TR-01 HIGH AI-Dri	TR-02 HIGH Circul	TR-03 MED Advanc	TR-04 MED Graphe	TR-05 LOW Advanc
Western OEM	0	++	+	+	++
Western Contract Manufacturer	+	+	++	++	0
Western T&M; Provider	++	+	+	+	0
Western Material Supplier	++	++	++	++	++
Western Distributor / Trading Company	0	++	+	+	0
Western Equipment Maker	+	+	++	++	+

Timeline This Week (8 Events)

Date	Tag	Headline	Source
2026-09-03	milestone	EU's BATRAW Project reduces EV battery disassembly time by 50-60%	EU S4-23
2026-09-04	product	Tesla unveils 'Cybercab' rare-earth-free EV motor	USA S1-23
2026-09-08	policy	FDA reaffirms medical fluoropolymers are safe, distinct from PFAS concerns	USA S2-16
2026-09-08	deal	Smart High Tech secures $10.5M from Henkel Ventures for graphene TIM production	Israel S4-08
2026-09-09	product	ProLogium initiates mass production of Gen 3.5 solid-state batteries (381 Wh/kg)	Taiwan S4-16
2026-09-10	milestone	Niron Magnetics breaks ground on rare-earth-free permanent magnet facility	USA S1-05
2026-09-10	milestone	PI Advanced Materials awarded for world's first 4µm polyimide film mass production	South Korea S1-01
2026-09-11	milestone	Imec and Taiyo Holdings achieve 700nm RDL formation for advanced packaging	Japan S4-20

Company Spotlight

Niron Magnetics ↑ Strategic Investment & Facility Groundbreaking

Honda's investment and new facility construction signal strong commercialization potential for rare-earth-free permanent magnets, critical for EV supply chain diversification.

- Western OEMs: Engage Niron for 2028 EV motor supply agreements.
- Western Material Suppliers: Explore partnership for raw material supply.

Graphene Manufacturing Group (GMG) [GMG] ↑ Stock Surges 4.03% on Battery Advances

GMG's long-life graphene-aluminum-ion battery data and modular plant commissioning indicate significant progress towards commercializing next-gen energy storage solutions.

- Western Investors: Evaluate GMG's long-term growth potential in energy storage.
- Western OEMs: Monitor GMG's battery performance for future integration.

Henkel [HEN.DE] ↑ Strategic Investments in Graphene TIMs & Sustainability

Henkel's $10.5M investment in Smart High Tech for graphene TIMs (S4-08) and Mentor plant upgrade for adhesive recovery (S4-25) demonstrate commitment to advanced materials and circularity.

- Western Equipment Makers: Partner with Henkel on advanced adhesive application systems.
- Western Material Suppliers: Collaborate on sustainable adhesive formulations.

Technology Roadmap

2026

- ◆ Mass production of Gen 3.5 solid-state batteries begins (ProLogium, S4-16)
- ◆ Epoxy-based debond-on-demand adhesives dominate EV battery modules (S4-29)

2027

- ◆ HydroGraph's commercial-scale graphene facility (360 tons/year) commences operations (S3-10)
- ◆ AI-driven material discovery platforms reduce R&D; cycle times by 20-30% (S1-10, S2-24)

2028

- ◆ Western OEMs target integration of rare-earth-free EV motors (S1-05, S1-23)
- ◆ Advanced composites achieve 40% weight reduction in automotive structural components (S2-26)

2029

- ◆ Advanced 3D printing services for high-performance polymers expand for aerospace/semiconductor (S2-01, S2-02)
- ◆ New testing & certification services for bio-based/recyclable materials capture $1B+ market (TR-02)

2030

- ◆ AI-driven materials discovery market reaches $2.77 billion (S1-10)
- ◆ Glass core substrates resolve AI accelerator warpage issues (S2-11)
- ◆ Graphene sensing chips market reaches $5.65 billion (S3-03)

References (120 Total)

ID	Title	Source	Date	Region	Sub-Topic
S1-01	PI Advanced Materials Awarded 2026 KPCA Industry Prize for World's First 4μm Polyimide Film Mass Production Technology	PI Advanced Materials (an Arkema Affiliate)	2026-09-10	South Korea	Functional Materials
S1-02	MIT Demonstrates Electrochemical Method for Efficiently Producing Pure Hydrogen from Ammonia	MIT News	2026-09-09	US	Functional Materials
S1-03	MIT Develops Injectable 'HITMAN' Nanoantennas for Drug-Resistant Glioblastoma, Significantly Suppressing Tumor Growth	MIT Media Lab / Science Advances	2026-09-09	US	Functional Materials
S1-04	Novel Multifunctional CeO□/U66@MXene Nanofiller Dramatically Enhances UV and Corrosion Resistance of Epoxy Coatings	European Coatings / Scienmag	2026-09-11	Germany	Functional Materials
S1-05	Niron Magnetics Breaks Ground on Rare-Earth-Free Permanent Magnet Manufacturing Facility, Honda Invests for EV Systems Adoption	PR Newswire	2026-09-10	US	Functional Materials
S1-06	ACS Publications Announces Durable Urchin-like Micro/Nanostructured Hydrophobic and Corrosion-Resistant Coating for Cultural Heritage Protection	ACS Publications	2026-09-10	US	Functional Materials
S1-07	Overcoming Transport Layer Bottlenecks for Ion Parameter Quantification in Perovskite Solar Cells, New Method Proposed	arXiv (Materials Science)	2026-09-10	Unknown	Functional Materials
S1-08	AutoXRD: Autonomous LLM Agents Proposed for Powder Diffraction Analysis, Enhancing Accuracy in Materials Science	arXiv (Materials Science)	2026-09-10	Unknown	Functional Materials
S1-09	Chromium Addition Reveals Trade-Off: Stronger Corrosion Shield, Softer Alloy in High-Entropy Metal	Bioengineer.org / Journal of Materials Science: Metallurgy	2026-09-11	Unknown	Functional Materials
S1-10	AI Becomes Central to Nanomaterials Discovery, Market Projected to Reach $2.77 Billion by 2030	nano-matter.com	2026-09-07	US	Functional Materials
S1-11	Columbia University Introduces New Benchmarks for Physics-Aware AI to Accelerate Materials Discovery	EurekAlert! / Columbia University School of Engineering and Applied Science	2026-09-08	US	Functional Materials
S1-12	Addressing AI Polymer Discovery Challenges: Blueprint for Autonomous Closed-Loop Ecosystem Devised	Asia Research News / JACS Au	2026-09-04	Unknown	Functional Materials
S1-13	PNAS Debates 'Synthetic Validity' Problem in AI-Generated Science, Pondering Impact on Materials Discovery	PNAS	2026-09-09	US	Functional Materials

ID	Title	Source	Date	Region	Sub-Topic
S1-14	Anhui Normal University Announces Li-Cl2 Battery with Over 97% Coulombic Efficiency, Published in Advanced Materials	Shanghai Metals Market / Advanced Materials	2026-09-11	China	Functional Materials
S1-15	Kyoto University iCeMS Develops Nature-Inspired PFAS-Free White Water-Repellent Material, Published in Nature	Kyoto University iCeMS / Nature	2026-09-09	Japan	Functional Materials
S1-16	BASF Unveils Advanced Polyurethane Materials for Durable, Circular Footwear Concepts at SIMAC 2026	BASF	2026-09-10	Germany	Functional Materials
S1-17	ChemRxiv Publishes Preprint on Colloidal Interactions in Low-Polarity Dispersions of Permanently Magnetic Nanoplatelets	ChemRxiv (Materials Science)	2026-09-07	Unknown	Functional Materials
S1-18	TAME: Reliable and Interpretable Molecular Property Prediction Model Unveiled on ChemRxiv	ChemRxiv (Materials Science)	2026-09-07	Unknown	Functional Materials
S1-19	ChemRxiv Announces Enhanced Visible-Light Water Splitting Efficiency via Spiral-Growth-Induced Nanosteps on Layered Oxyhalide Photocatalysts	ChemRxiv (Materials Science)	2026-09-06	Unknown	Functional Materials
S1-20	ChemRxiv Announces Machine-Learned Solid-State ^{13}C Chemical Shifts for Structure-Resolved Polymer Simulations	ChemRxiv (Materials Science)	2026-09-06	Unknown	Functional Materials
S1-21	Union College Researchers Establish New Principles for Solvent-Controlled Chiral Polymer Assemblies, Advancing High-Performance Electronics	Union College / Advanced Materials	2026-09-10	US	Functional Materials
S1-22	Penn State and Kurt J. Lesker Company Partner to Establish ASPIRE Center, Jointly Advancing Atomic-Scale Processing Technologies	Penn State News	2026-09-10	US	Functional Materials
S1-23	Tesla Unveils Rare-Earth-Free EV Motor 'Cybercab,' Achieving 18% Smaller, 25% Lighter Design with Significant Power Density Boost	Electrek	2026-09-04	US	Functional Materials
S1-24	Preprints.org Releases New Chemistry and Materials Science Preprints on Lithium Extraction and Nickel Coating	Preprints.org	2026-09-09	Unknown	Functional Materials
S1-25	Argonne National Laboratory Successfully Synthesizes First Borophene, a Metallic Single-Atom-Thick Boron, Opening New Era for 2D Materials	Argonne National Laboratory	2026-09-08	US	Functional Materials
S1-26	Same Sky Unveils High-Endurance SPG Thermoelectric Modules Generating Up to 27.3W from Waste Heat	Electronics For You	2026-09-10	India	Functional Materials

ID	Title	Source	Date	Region	Sub-Topic
S1-27	ChemRxiv Preprint "IQARIS" Integrates Quantum Chemistry Datasets with Machine Learning to Accelerate New Material Design through Large-Scale Local Quantum Information Exploration	ChemRxiv	2026-09-03	US	Functional Materials
S1-28	ChemRxiv Preprint Applies Tree Models, ChemBERTa, Graph Networks, and Late Fusion for Plasma Protein Binding Prediction under Scaffold Split, Enhancing Drug Discovery Efficiency	ChemRxiv	2026-09-09	US	Functional Materials
S2-01	Bilby3D Unveils High-Temperature 3D Printing Filaments, Including ThermaX PEEK/TPI, for Aerospace and Automotive Sector Operating Above 120°C	Bilby3D	2026-09-07	Australia	Polymers & Resins
S2-02	INTAMSYS and JLC3DP Launch Scalable PEEK and PEKK 3D Printing Services for Aerospace and Semiconductor Applications	INTAMSYS / JLC3DP	2026-09-09	China	Polymers & Resins
S2-03	Sumitomo Chemical and Gutenberg Co-Develop Liquid Crystal Polymer Filament for 3D Printing in Semiconductor and AI Applications	Plastics Today	2026-09-10	Japan	Polymers & Resins
S2-04	Novel Hyperbranched Polyphenylsiloxane-Modified Epoxy Resin Achieves Dielectric Constant of 2.82 and Dissipation Factor of 0.02050 at 100 MHz for Electronic Packaging	ACS Publications	2026-09-07	US	Polymers & Resins
S2-05	Comprehensive Review on Sustainable Polymer Additive Manufacturing Published by MDPI, Advocating Multi-Faceted Evaluation of Performance, Processing Burden, and Recyclability	MDPI	2026-09-10	Switzerland	Polymers & Resins
S2-06	ACS Review Highlights 'Functionalization Paradox' in Sustainable AM, Cautioning Against Increased Carbon Footprint from Bio-Derived Materials' Chemical Modification	ACS Publications	2026-09-07	US	Polymers & Resins
S2-07	JLC3DP Clarifies PLA's Practical Heat Resistance Limit for 3D Printing at Below 50-60°C, Recommends High-Performance Materials for Elevated Temperatures	JLC3DP	2026-09-03	China	Polymers & Resins
S2-08	Researchers Develop Multi-Layer Metal and Ceramic Coatings for 3D-Printed Polymer Parts, Significantly Enhancing Wear Resistance and Adhesion	AZoM	2026-09-11	UK	Polymers & Resins
S2-09	NIST Commercializes New 3D-Printing Reference Material RM 8047 to Standardize Photopolymer Manufacturing, Enhancing Quality Control and Reproducibility	WhatTheyThink	2026-09-11	US	Polymers & Resins

ID	Title	Source	Date	Region	Sub-Topic
S2-10	ZAECOTECH Elucidates Mechanical Properties of Biomass-Derived Thermosets for Wind Blades, Paving Way for Closed-Loop Recycling	ZAECOTECH	2026-09-11	Germany	Polymers & Resins
S2-11	Glass Core Substrates Poised to Resolve Warpage Issues in Data Center AI Accelerators by 2030, Addressing ABF Substrate Limitations	Tom's Hardware	2026-09-10	US	Polymers & Resins
S2-12	Sucrose-Assisted Boron Nitride Interface Engineering Yields BT-Based High-Frequency Substrates with Ultra-Low Dielectric Loss of 0.003 at 10 GHz and Enhanced Thermal Conductivity	ACS Publications	2026-09-10	US	Polymers & Resins
S2-13	PEEK Adoption Accelerates in Semiconductor Equipment: Exceptional Purity, Thermal Performance, and Chemical Resistance Drive Wafer Handling Advancements	Poly Fluoro Ltd	2026-09-09	India	Polymers & Resins
S2-14	TOWA Contributes to AI Semiconductor Thermal Management and Productivity with 'Mold Underfill (MUF)' Technology via US-JOINT Platform	Resonac	2026-09-11	Japan	Polymers & Resins
S2-15	Novel Recycling Technology Decomposes Carbon Fiber-Reinforced Polybenzoxazine Composites, Recovers Carbon Fibers with Minimal Damage	ACS Publications	2026-09-03	US	Polymers & Resins
S2-16	FDA Solidifies Distinction: Medical Fluoropolymers Deemed Safe, Exempt from Broad PFAS Concerns	Mondaq	2026-09-08	US	Polymers & Resins
S2-17	Avantium Partners with Sojitz Pla-Net to Propel Plant-Based PEF "releaf®" Adoption in Japanese Market	Avantium N.V. (Press Release)	2026-09-08	Netherlands	Polymers & Resins
S2-18	WHILL's New 'Model C Lite' Personal Mobility Incorporates Teijin's Thermoplastic Carbon Fiber Composite, Achieving an Ultra-Light 18.6kg	MONOist	2026-09-03	Japan	Polymers & Resins
S2-19	Teijin Revolutionizes CFRP: Self-Healing, Highly Recyclable Thermoset Material Poised for Sustainable High-Performance Applications	環境ビジネスオンライン	Published September 06, 2026	Japan	Polymers & Resins
S2-20	Albion Adopts Mitsubishi Chemical's Plant-Derived Bio-Engineering Plastic "DURABIO" for Cosmetic Compact Cases	MONOist	2026-09-04	Japan	Polymers & Resins
S2-21	Mitsubishi Chemical Elevates DURABIO: A Bio-Engineering Plastic Pushing Performance and Sustainability Boundaries	三菱ケミカル株式会社	Published September 05, 2026	Japan	Polymers & Resins
S2-22	Shinshu University Unveils PFAS-Free Fuel Cell Membrane, Achieving 100,000 Cycles at 120°C for Next-Gen PEFCs	信州大学繊維学部	Published September 08, 2026	Japan	Polymers & Resins

ID	Title	Source	Date	Region	Sub-Topic
S2-23	Revolutionizing Composites: Nagoya Tech's Solid Catalyst Recovers High-Quality Carbon Fibers from CFRP Waste	名古屋工業大学	2026-09-09	Japan	Polymers & Resins
S2-24	Georgia Tech Pioneers Generative AI for Polymer Design, Accelerating Discovery and Slashing R&D; Costs	—	2026-09-08	US	Polymers & Resins
S2-25	DuPont Supercharges Vespel® R&D; in Japan to Meet Soaring Electronics Demands	Kagaku Kogyo Nippo (JP)	2026-09-07	Japan	Polymers & Resins
S2-26	Teijin Revolutionizes Automotive Lightweighting with Sereebo®: A Mass-Produced Carbon Composite Offering 40% Weight Reduction and 10x Impact Resistance	帝人株式会社	2026-09-04	Japan	Polymers & Resins
S2-27	High-Toughness CFRP from Toray Revolutionizes Aircraft Fuel Efficiency and Emissions Reduction	新化学技術推進協会	2026-09-09	Japan	Polymers & Resins
S2-28	Sigma-Aldrich Enhances Fuel Cell Polymer Electrolyte Membranes: Enabling Low-Temperature Operation and High Durability to Advance PEFC Technology	Sigma-Aldrich	2026-09-08	US	Polymers & Resins
S2-29	Kanazawa University's Dr. Tatsuno Details How Thermoplastic Composites (CFRTP) Are Poised to Revolutionize Automotive Mass Production	Style	2026-09-10	Japan	Polymers & Resins
S3-01	First Graphene Secures Inaugural PureGRAPH® Production Order from Pacific Urethanes for Enhanced Fire-Retardant Polyurethane in Australian Mining	MineListings.com	2026-09-10	Australia	Nanotechnology
S3-02	Graphene Transitions to Commercialization Across Medical Biosensors, Energy Storage, and Industrial Coatings	Revolutionized	2026-09-03	US	Nanotechnology
S3-03	Graphene Sensing Chips Advance to Commercial Testing: Paragraf Launches GFET Platform, Market Projected to Reach $5.65 Billion by 2036	openPR.com	2026-09-04	UK	Nanotechnology
S3-04	University of Manchester Study Provides Strong Evidence for Electron Interaction's Central Role in Graphene's Unconventional Superconductivity	The University of Manchester, EurekAlert!	2026-09-08	UK	Nanotechnology
S3-05	Chinese Researchers Develop MXene/Fe3S4@FeSe2 Heterojunctions, Achieving 450 mAh/g Initial Capacity in Sodium-Ion Batteries	Journal of Functional Materials	2026-08	China	Nanotechnology
S3-06	Graphene Manufacturing Group Reports Long-Life Cycling Data for Graphene-Aluminum-Ion Batteries, Commissions Modular Production Plant	Facebook (Graphene Manufacturing Group)	2026-09-09	Australia	Nanotechnology

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S3-07	Chinese Researchers Develop ZrB2/MXene Composite for Li-S Battery, Achieving 1395.9 mA·h/g Initial Capacity and 0.072% Decay Rate Over 500 Cycles	Journal of Materials Science: Materials in Electronics	2026-09-09	China	Nanotechnology
S3-08	Vertically Aligned MXene-ZnNi2S4-ZnNi2O4 Nanoflake Ensemble Achieves 329.1 F/g Capacitance for Multifunctional Energy Storage Cathode	Nanoscale | The Royal Society of Chemistry	2026-09-08	UK	Nanotechnology
S3-09	U.S. Department of Energy Funds Coal-Derived Graphene Research for Conductors, Batteries, and Motors	Department of Energy	2026-09-03	US	Nanotechnology
S3-10	HydroGraph Opens Texas Headquarters, Establishing 30-Ton Annual Graphene Production Capacity with Hyperion Reactor™ Technology	PCI Magazine	2026-09-09	US	Nanotechnology
S3-11	Avadain's LTDF Graphene to Revolutionize Industrial 3D Printing, Enabling 20-40% Weight Reduction in Aerospace	EIN Presswire	2026-09-06	US	Nanotechnology
S3-12	Vienna Scientists Achieve Atomic-Precision Nanopore Sculpting in 'White Graphene' for Breakthrough Applications	University of Vienna, Scientific Frontline	2026-09-10	Austria	Nanotechnology
S3-13	Georgia Tech and Tianjin University Develop World's First Functional Graphene Semiconductor with 10x Silicon's Electron Mobility, Compatible with Existing Chip Infrastructure	Iron Circuit (YouTube)	2026-09-10	USA、China	Nanotechnology
S3-14	Industrial Leap: High-Yield GFETs on 200mm Wafers Accelerate Graphene's CMOS Integration	ACS Publications	2026-09-09	Belgium	Nanotechnology
S3-15	Graphene Flagship's 2D Pilot Line Develops Graphene PICs on 200mm Wafers, Demonstrating Scalability for Industrial Photonics Adoption	Graphene Flagship	2026-09-20	EU	Nanotechnology
S3-16	Nanoimprint Lithography Poised to Break Manufacturing Barriers in Nano-Optics, Highlighted at CIOE 2026	CIOE (China International Optoelectronic Expo)	2026-09-10	China	Nanotechnology
S3-17	Zymosense Secures $92,000 RuralSTAMINA Grant to Accelerate Phytase Commercialization	PRWeb	2026-09-08	US	Nanotechnology
S3-18	First Graphene Updates ASX with Securities Listing Application and Director Interest Changes, Signifying Ongoing Corporate Activity	First Graphene (ASX Announcements)	2026-09-08	Australia	Nanotechnology
S3-19	Imec Achieves Record 3.8M Junction/cm^2 Density in Superconducting Circuits with 30nm NbTiN Interconnects, Propelling Next-Gen HPC/AI	imec	2026-09-07	Belgium	Nanotechnology

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S3-20	Novel Aramid Nanofiber Aero-gel Achieves Ultra-Low Thermal Conductivity of 25.17 mW m⊠¹ K⊠¹ and Extreme Temperature Durability (-196°C to 400°C), Revolutionizing Harsh Environment Insulation	Materials Horizons | The Royal Society of Chemistry	2026-09-10	UK	Nanotechnology
S3-21	Allegro's Nanotechnology Therapeutic, Hydrocelin, Achieves Statistically Significant Improvement in Knee Osteoarthritis Pain and Function Over Six Months in Clinical Trials	GlobeNewswire	2026-09-09	Unknown	Nanotechnology
S3-22	Mayo Clinic and NaNotics Demonstrate NaNots Nanoparticles Restore Anti-Tumor Immunity and Significantly Delay Tumor Growth in Triple-Negative Breast Cancer	Business Wire	2026-09-09	US	Nanotechnology
S3-23	Imec Unlocks 22nm Pitch Single Patterning for High NA EUV Lithography, Accelerating Next-Gen Microchip Manufacturing	imec	2026-09-08	Belgium	Nanotechnology
S3-24	Cerium-Doped Bioactive Glass Nanofibers Effectively Promote Bone Regeneration by Enhancing Treg-Mediated Immunomodulation	Regenerative Biomaterials | Oxford Academic	2026-09-07	Unknown	Nanotechnology
S3-25	Novel Bilayer Collagen Nanofiber Nerve Wrap Promotes Axonal Regeneration and Myelination in Canine Peripheral Nerve Injury Model, Outperforming or Matching Commercial Devices	Regenerative Biomaterials | Oxford Academic	2026-09-07	Unknown	Nanotechnology
S3-26	Machine Learning Force Fields Unravel Carboxylate Ligand Binding on CdSe Quantum Dots at Atomic Level, Paving Way for Enhanced Displays, Solar Cells, and Bioimaging	Scienmag	2026-09-05	Unknown	Nanotechnology
S3-27	Clay-Reinforced Blow-Spun PVDF Nanofiber Mats Achieve Significant Mechanical Strength Enhancement Up to a Critical Limit, Opening New Horizons for Functional Membrane Applications	Scienmag	2026-09-11	Unknown	Nanotechnology
S3-28	MIT Researchers Develop Injectable Nanodevices for Drug-Resistant Glioblastoma, Offering New Strategy for Infiltrative Tumors by Crossing Blood-Brain Barrier and Evading Immune System	Medical Xpress	2026-09-09	US	Nanotechnology
S3-29	Graphene Manufacturing Group (GMG) Stock Surges 4.03% as Advances in Graphene Aluminum-Ion Battery Technology Fuel Investor Interest	Kalkine CA	2026-09-10	Canada	Nanotechnology
S3-30	First Graphene Secures Landmark Production Order for PureGRAPH® from Pacific Urethanes for Mining Fire-Resistant Products	First Graphene	2026-09-08	Australia	Nanotechnology

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S3-31	ACS Fall 2026 Unveils Breakthrough in Inherently Safer, Hydrofluoric Acid-Free MXene Production Accelerating Commercialization	American Chemical Society	Date unknown	US	Nanotechnology
S4-01	Oak Ridge National Lab Develops Reusable Adhesive from Waste Polymers, Effective in Both Wet and Dry Conditions	Adhesives & Sealants Industry	2026-09-10	US	Adhesives & Encapsulants
S4-02	Sika AG Completes Acquisition of Turkish Adhesives & Sealants Leader Akkim, Bolstering East European and Middle Eastern Market Presence by CHF 220 Million Annual Revenue	Plasticker	2026-09-03	Germany	Adhesives & Encapsulants
S4-03	Q.E.P. CO., INC. Acquires Spray-Lock, Expanding Low-VOC Spray Adhesive Manufacturing Platform	Q.E.P. CO., INC.	2026-09-08	US	Adhesives & Encapsulants
S4-04	JBC Technologies Acquires NADCO Tapes & Labels, Expanding Adhesive Component Business for Medical and Wearable Devices	Packaging Gateway	2026-09-10	US	Adhesives & Encapsulants
S4-05	Caly Technologies Releases TIM Selection Guide for Power Electronics, Optimizing Thermal Management for SiC and GaN Devices	Alibaba Electronics	2026-09-03	China	Adhesives & Encapsulants
S4-06	Cambium Unveils ApexFrame 5000, a High-Temperature Laminating Film Adhesive for Aerospace and Defense, Withstanding Over 315°C	PR Newswire (via Cambium)	2026-09-03	US	Adhesives & Encapsulants
S4-07	CHT-Silicones Unveils Silso protect 21190 A/B: A 2-Component Low-Flammability Silicone Elastomer for Electronic Potting and Encapsulation	CHT-Silicones	2026-09-06	Germany	Adhesives & Encapsulants
S4-08	Smart High Tech Secures $10.5M from Henkel Ventures to Propel Graphene TIM Production for Next-Gen Electronics	Graphene-Info	Published September 08, 2026	Israel	Adhesives & Encapsulants
S4-09	Automotive Industry Innovates Assembly Efficiency and Durability in 2026 with Structural Adhesives for Aluminum and Composites	B8X	2026-09-08	Germany	Adhesives & Encapsulants
S4-10	CTX Thermal Solutions Expands TIM Portfolio with Thermal Pads, Graphite Foils for 5G, EV, and Medical Applications	SJN (Semiconductor Journal Network)	2026-09-10	US	Adhesives & Encapsulants
S4-11	Indium Corporation to Showcase Advanced Materials for AI at SEMICON Taiwan, Including High-Thermal-Conductivity Sintering Pastes and TIMs	Indium Corporation	2026-09-10	US	Adhesives & Encapsulants
S4-12	HakTak Lays Out Thermal Putty's Critical Role in Optimizing EV Battery and Inverter Thermal Management	HakTak	2026-09-09	US	Adhesives & Encapsulants

ID	Title	Source	Date	Region	Sub-Topic
S4-13	Apple Unveils 2nm iPhone 18; Samsung Cuts Thermal Resistance by 16% with Encapsulant and TIM Innovations, Intensifying Competition with TSMC	BigGo Finance	2026-09-10	South Korea	Adhesives & Encapsulants
S4-14	AZoM Explains Polyimides' Indispensable Role in Semiconductor Packaging, Critical for HBM and Chiplet RDLs	AZoM	2026-09-08	UK	Adhesives & Encapsulants
S4-15	H.B. Fuller Schedules Q3 2026 Earnings Release for September 23	Business Wire / H.B. Fuller	2026-09-09	US	Adhesives & Encapsulants
S4-16	ProLogium Initiates Mass Production of Gen 3.5 Solid-State Batteries with 381 Wh/kg Energy Density for EVs	Electric Cars Report	2026-09-09	Taiwan	Adhesives & Encapsulants
S4-17	LG Energy Solution and Seoul National University Achieve LMR Battery Large-Cell Stability Breakthrough for Reduced Cobalt and Enhanced Cost Competitiveness	Korea IT Times	2026-09-07	South Korea	Adhesives & Encapsulants
S4-18	Wausau Coated Products Unveils WA-669 Wash-Away Label Adhesive for Easy Debonding on Reusable Glass Bottles	Packaging Gateway	2026-09-09	US	Adhesives & Encapsulants
S4-19	Dymax to Showcase High-Efficiency, Reliable Adhesion and Curing Solutions for Medical Device Manufacturing at Medical Technology Ireland 2026	Dymax	2026-09-10	US	Adhesives & Encapsulants
S4-20	Taiyo Holdings and imec Achieve 700nm RDL Formation for Advanced Packaging, Accelerating AI and HPC Chip Performance	ChemAnalyst	2026-09-11	Japan	Adhesives & Encapsulants
S4-21	Sika Completes Akkim Acquisition, Significantly Strengthening Global Adhesives and Sealants Business	GlobeNewswire / Sika AG	2026-09-03	Switzerland	Adhesives & Encapsulants
S4-22	Virginia Tech Develops Monomaterial Adhesive Tape Outperforming Duct Tape with Chemical Recyclability	Packaging Insights	2026-09-08	US	Adhesives & Encapsulants
S4-23	EU's BATRAW Project Develops Semi-Automated EV Battery Recycling Technology, Reducing Disassembly Time by 50-60%	CORDIS	2026-09-03	EU	Adhesives & Encapsulants
S4-24	Itaconate Chemistry and Nanocellulose Reinforcement Optimize Adhesion-Cohesion Balance in High Bio-Content Waterborne PSAs	ACS Publications	2026-09-09	US	Adhesives & Encapsulants
S4-25	Henkel's Mentor Site Upgrade Boosts SMP Moisture-Curing Adhesive Recovery, Drives Sustainable Production by Reducing Manufacturing Waste	openPR.com	2026-09-03	Germany	Adhesives & Encapsulants
S4-26	Cobalt-Catalyzed Polymerization Enables Switchable Pressure-Sensitive Adhesion with Soft Methacrylate Nematic Elastomers	ACS Publications	2026-09-08	US	Adhesives & Encapsulants

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S4-27	Sun Chemical and Cyngient Announce Strategic Narrow Web Partnership, Launching Joint Specialty Coatings and High-Performance Adhesives	Sun Chemical	2026-09-10	US	Adhesives & Encapsulants
S4-28	Dymax Launches BlueWave® FX Line Emitters for High-Speed UV/Visible Curing, Boosting Throughput with up to 4.2 W/cm²	Taiwan News / Dymax	2026-09-10	US	Adhesives & Encapsulants
S4-29	Epoxy-Based Debonding-on-Demand Adhesives to Dominate EV Battery Module Market in 2026	openPR.com	2026-09-11	US	Adhesives & Encapsulants
S4-30	B8X Drives Automotive Innovation with 2026 Structural Adhesives: Lightweighting, Eco-Friendly, and Self-Healing Capabilities	B8X	2026-09-08	Unknown	Adhesives & Encapsulants
S4-31	2026 Adhesive Industry Trends: Wash-Off/Recyclable Adhesives, Bio-Based Hot Melts, and Debond-on-Demand Solutions Driven by Right to Repair Movement	Accio	2026-09-06	Unknown	Adhesives & Encapsulants
S4-32	Henkel Unveils New Flame-Retardant Sealant and Debonding Solutions for Rail Vehicle Lifecycle at InnoTrans 2026	Henkel	2026-09-04	Germany	Adhesives & Encapsulants

Editor's Note

Navigating the Materials Revolution: Strategic Imperatives for Western Leadership

The current landscape of Materials & Chemistry is defined by an unprecedented convergence of technological breakthroughs and market demands for sustainability. AI is not merely an optimization tool but a fundamental accelerator, compressing material discovery cycles from years to hours. Western manufacturers and investors must recognize this paradigm shift, moving beyond incremental improvements to embrace AI-driven R&D; platforms as a core strategic capability. Early adoption and investment in these platforms will dictate future competitive advantage, particularly in high-value segments like advanced electronics and next-gen energy storage.

The push towards a circular economy is reshaping material design from first principles. From rare-earth-free magnets to chemically recyclable adhesives and bio-based polymers, sustainability is no longer a niche concern but a critical performance metric. Western players have a unique opportunity to lead in this transition by investing in closed-loop recycling technologies, developing PFAS-free alternatives, and fostering partnerships across the value chain to create truly circular material ecosystems. This requires a proactive approach to R&D;, supply chain re-evaluation, and robust regulatory engagement to establish new standards.

Strategic positioning in advanced manufacturing, especially for semiconductors and EVs, hinges on mastering complex material interactions and thermal management. The demand for higher performance and miniaturization in AI accelerators necessitates innovations in ultra-low dielectric resins, advanced packaging, and graphene-enhanced thermal interface materials. Western equipment makers and material suppliers must collaborate closely with foundries and OEMs to co-develop integrated solutions, ensuring that the foundational materials infrastructure supports the ambitious performance targets of future technologies. This integrated approach will be key to securing Western competitiveness.

◆ How can Western manufacturers best leverage AI-driven material discovery platforms to reduce R&D; costs and accelerate time-to-market by 30% within 24 months?

◆ What specific investments in circular economy infrastructure (e.g., advanced recycling, bio-based feedstock processing) are required to achieve a 50% reduction in material waste by 2030?

◆ How can Western players establish a dominant position in advanced semiconductor packaging materials and thermal management solutions to support 2nm chip production by 2028?

Troy Technical Weekly Editorial Board Chief Analyst

Next Issue Vol. 58 Monday, September 21, 2026 06:00 JST Feature: Sustainable Manufacturing & Circular Economy

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